PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| In re application of Curcio et al | ) | Examiner: |
| | ) | |
| Serial No.: To be assigned | ) | Art Unit: |
| | ) | |
| Filed: Herewith | ) | |
| | ) | |
| For: **METHOD AND STRUCTURE FOR PRODUCING Z-AXIS INTERCONNECTION ASSEMBLY OF PRINTED WIRING BOARD** | ) | |

Docket No. END920000122US1 (IEN-10-5530)

## INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This Information Disclosure Statement is being filed to fulfill the duty of candor and good faith toward the Patent and Trademark Office, as required pursuant to 37 C.F.R. § 1.56.

Listed on the attached PTO form 1449 is information known to persons substantively involved in the preparation of the application identified above, and that a reasonable Examiner would consider important when deciding whether to allow the application. This document is not to be construed as a representation that a search to locate the most relevant information has been made, nor a representation that more pertinent information does not exist.

Copies of the information listed on the attached PTO Form 1449 are provided herewith.

The identification of any information herein is not intended to be, and should not be understood as being, an admission that such information, in fact, constitutes "prior art" within the meaning of applicable law. The "prior art" status of any information is a matter to be resolved during prosecution.

This Information Disclosure Statement is being filed the application. Accordingly, it is not believed that any fee is required relating to the filing of this Information Disclosure Statement. If this is not the case, the Patent Office is hereby authorized to charge any related fee to Deposit Account No. 03-0172.

Respectfully submitted,

Date: 3-8-01

By: _____

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enclosures

| Subst. Form PTO-1449<br><br>APPLICANT'S INFORMATION DISCLOSURE STATEMENT | Atty. Docket No.: END920000122US1 (IEN-10-5530) | Serial No.: To be assigned |
|---|---|---|
| | Applicant: Curcio et al | |
| | Filing Date: Herewith | Group: |

## U.S. PATENT DOCUMENTS

| Initial* | | Document No. | Date | Name | Class | Subcl. | Filing Date |
|---|---|---|---|---|---|---|---|
| | AA | 3,795,047 | 03/05/74 | Abolafia et al | 29 | 625 | 06/15/72 |
| | AB | 5,092,032 | 03/03/92 | Murakimi | 29 | 830 | 05/15/91 |
| | AC | 5,135,606 | 08/04/92 | Kato et al | 156 | 631 | 12/07/90 |
| | AD | 5,200,026 | 04/06/93 | Okabe | 156 | 651 | 05/15/91 |
| | AE | 5,322,593 | 06/21/94 | Hasegawa et al | 156 | 633 | 11/20/92 |
| | AF | 5,624,268 | 04/29/97 | Maeda et al | 439 | 66 | 01/17/96 |
| | AG | 5,819,406 | 10/13/98 | Yoshizawa et al | 29 | 877 | 07/30/96 |
| | AH | 5,984,691 | 11/16/99 | Brodsky et al | 439 | 66 | 03/10/98 |
| | AI | 6,059,579 | 05/09/00 | Kresge et al | 439 | 66 | 09/24/97 |
| | AJ | | | | | | |
| | AK | | | | | | |

## FOREIGN PATENT DOCUMENTS

| | | Document No. | Date | Country | Class | Subcl. | Translation? |
|---|---|---|---|---|---|---|---|
| | AL | | | | | | |
| | AM | | | | | | |
| | AN | | | | | | |

## OTHER DOCUMENTS

| | | |
|---|---|---|
| | AO | U.S. Application of Appelt et al for "Manufacturing Methods for Printed Circuit Boards and Printed Circuit Boards Made Thereby", Serial No. 08/968,988 (IBM Docket EN9-97-032) |
| | AP | U.S. Application of Lauffer et al for "Composite Laminate Circuit Structure and Methods of Interconnecting the Same" (IBM Docket EN9-99-081) |
| | AQ | IBM Technical Disclosure Bulletin, Vol. 37, No. 02A, "Improved and Cost-Reduced Interposer for Higher-Risk Processes", February, 1994 |
| | AR | "Multi Layer Substrate with Low Coefficient of Thermal Expansion", Kei Nakamura et al, 2000 International Symposium on Microelectronics, pp 235-240 |
| | AS | |
| | AT | |

| Examiner: | Date Considered: |
|---|---|

*EXAMINER: Initial if reference considered, whether or not citation is in conformation with MPEP 609; draw line through citation if in conformance and not co[illegible] of this form with next communication to applicant.